EMVCo: Collaborating for Seamless and Secure Payments Worldwide

EMVCo engages and collaborates with hundreds of organizations, technical bodies and regulators to develop EMV® Specifications that support innovation and address marketplace needs. This results in specifications used across the payments industry to create products and services that deliver trusted and convenient payments for merchants and consumers in the U.S. and around the world.

Industry Participation and Input

- Payments technology continues to advance, and innovation in card-based payments is critical. To support seamless and secure payments, specifications need to evolve accordingly. This requires payments industry stakeholders to provide feedback throughout the specification development process.
- Through the EMVCo Associates and Subscriber Programs, merchants, issuers, acquirers, payment networks, financial institutions, manufacturers, technology providers and testing laboratories contribute their knowledge and expertise to the development of EMV Specifications.
- EMV Specifications are publicly available for use by any organization, and all payments industry stakeholders are encouraged to contribute to the development of EMV Specifications and provide input to EMVCo. To enable this participation, all new EMV Specifications and major updates are released for public review to enable all parties to provide comments before final publication.

DID YOU KNOW?

- Payments industry stakeholders can contribute to EMVCo’s work through participation in:
  - EMVCo’s Board of Advisors to propose new initiatives and vote on whether a final draft of a new specification or major update is ready for official publication.
  - Regular EMVCo advisory and technical meetings to develop, enhance and evolve EMV Specifications.
  - Review and comment periods for draft EMV Specifications.

Specification Development Process

- Specification Development Process:
  - New Spec or Major Spec revision proposed
  - EMVCo agrees to progress
  - Business Special Interest Meeting
  - Draft(s) prepared by EMVCo Working Group
  - Technical Special Interest Meeting(s)
  - Subscriber and Public RFC and Disposition of Comments
  - Final Draft ready for Subscriber and Public Review
  - Testing available for 3rd party products based on the specification
  - Advisers approve Specification for release
  - Final Specification published
  - If applicable, test scripts made available to Labs
  - If applicable, qualification process for tools and Labs
  - Final Draft updated with feedback received
  - Business Special Interest Meeting
  - Draft(s) prepared by EMVCo Working Group
  - Technical Special Interest Meeting(s)
  - Subscriber and Public RFC and Disposition of Comments
  - Final Specification published
  - EMVCo confirms final draft consistent with original goal

For more information on EMVCo please visit: www.emvco.com

EMV® is a registered trademark in the U.S. and other countries and an unregistered trademark elsewhere. The EMV trademark is owned by EMVCo, LLC.
Debit Transaction Routing – U.S. Payments Forum (USPF)

Worked with the USPF to demonstrate how the flexibility of the EMV Chip Specifications supported the U.S. payment industry's need for a Common Debit AID on chip cards, to provide merchants debit routing options in accordance with U.S. regulation.

Web Payment Security Interest Group – FIDO Alliance and World Wide Web Consortium (W3C)

Industry working group established with FIDO Alliance and W3C, focused on making web payments secure and convenient for merchants and consumers.

EMV 3-D Secure (3DS) and FIDO Authentication – FIDO Alliance

Collaborative initiative with FIDO Alliance, focused on evaluating how FIDO authentication standards and EMV Specifications can work together to help merchants reduce fraud and improve the online payment experience for consumers.

As EMVCo Associates, we immediately saw the benefit of extending EMV 3DS authentication request messages with airline information. The travel industry is somewhat different from other e-commerce businesses due to the prevalence of distribution channels and the complexity of booking several travel segments from different providers in one purchase. We worked together to examine specific travel use cases to understand the data transmitted at specific touch points. Being able to leverage existing data allows merchants to share more insight on travel transactions and supports issuers in fighting fraud while also reducing friction when processing travel payments. Right now, it is even more important our industry combats fraud and keeps payment friction to a minimum. This new EMV 3DS Travel Industry Message Extension from EMVCo will help achieve that objective.

This [Use of FIDO Data in 3DS Messages] paper, as well as FIDO Alliance’s complementary technical note, provides essential information on how FIDO can be used alongside EMV 3DS to provide higher levels of security, enhanced user experiences, and better overall approval rates for e-commerce merchants. These papers are part of our long-standing relationship with EMVCo and our shared focus on providing answers to the questions we often receive on how our FIDO Alliance standards and EMVCo specifications can work together.

Jean-Christophe Lacour, Head of Merchant Services, Payments, aMaDEUS

For more than 25 years W3C has developed open standards for Web technology. When W3C began to focus on streamlining e-commerce checkout, EMVCo and W3C recognized the value of developing an industry partnership. With the FIDO Alliance we then established a dedicated Web Payment Security Interest Group. All three organizations now work more closely to improve online payment security and to enhance interoperability among our respective technologies. Through this collaboration we anticipate that merchants, payment service providers, and other industry stakeholders will benefit from more secure and streamlined online payments. In response to industry queries, we have also published an introduction titled ‘How EMVCo, FIDO, and W3C Technologies Relate.’

Christina Hulka, Executive Director and COO

Ian Jacobs, Payments Lead

Randy Vanderhoof, Executive Director

The U.S. Payments Forum has worked closely with EMVCo over the years in our efforts to support the introduction and implementation of EMV chip and other new and emerging technologies that protect the security of, and enhance opportunities for payment transactions within the U.S., including EMV Tokenization, EMV 3-D Secure (3DS) and EMV Secure Remote Commerce (SRC).